



FQD12N06

60V N-Channel MOSFET

General Description

The FQD12N06 combine advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. Those devices are suitable for use in PWM, load switching and general purpose applications.

Product Summary

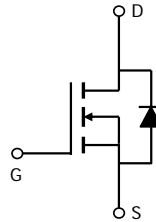
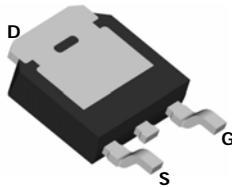
V_{DS}	60V
I_D (at $V_{GS}=10V$)	12A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 65m Ω
$R_{DS(ON)}$ (at $V_{GS} = 4.5V$)	< 85m Ω

100% UIS Tested
100% Rg Tested



TO252
DPAK

Bottom View



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^G	I_D	$T_C=25^\circ\text{C}$	12
		$T_C=100^\circ\text{C}$	9
Pulsed Drain Current ^C	I_{DM}	30	A
Continuous Drain Current	I_{DSM}	$T_A=25^\circ\text{C}$	4
		$T_A=70^\circ\text{C}$	3
Avalanche Current ^C	I_{AS}, I_{AR}	19	A
Avalanche energy $L=0.1\text{mH}$ ^C	E_{AS}, E_{AR}	18	mJ
Power Dissipation ^B	P_D	$T_C=25^\circ\text{C}$	20
		$T_C=100^\circ\text{C}$	10
Power Dissipation ^A	P_{DSM}	$T_A=25^\circ\text{C}$	2.1
		$T_A=70^\circ\text{C}$	1.3
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	17.4	30	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^{A D}				
Maximum Junction-to-Case	$R_{\theta JC}$	4	7.5	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0V	60			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =48V, V _{GS} =0V T _J =55°C			1 5	μA
I _{GSS}	Gate-Body leakage current	V _{DS} =0V, V _{GS} = ±20V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} I _D =250μA	1	2.4	3	V
I _{D(ON)}	On state drain current	V _{GS} =10V, V _{DS} =5V	30			A
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =6A T _J =125°C		67 85	75 100	mΩ
		V _{GS} =4.5V, I _D =6A		67	85	mΩ
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		14		S
V _{SD}	Diode Forward Voltage	I _S =1A, V _{GS} =0V		0.74	1	V
I _S	Maximum Body-Diode Continuous Current				12	A
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =30V, f=1MHz	360	450	540	pF
C _{oss}	Output Capacitance		40	61	80	pF
C _{rss}	Reverse Transfer Capacitance		16	27	40	pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1MHz	0.6	1.4	2.0	Ω
SWITCHING PARAMETERS						
Q _{g(10V)}	Total Gate Charge	V _{GS} =10V, V _{DS} =30V, I _D =12A		7.5	10	nC
Q _{g(4.5V)}	Total Gate Charge			3.8	5	nC
Q _{gs}	Gate Source Charge			1.2		nC
Q _{gd}	Gate Drain Charge			1.9		nC
t _{D(on)}	Turn-On DelayTime	V _{GS} =10V, V _{DS} =30V, R _L =2.5Ω, R _{GEN} =3Ω		4.2		ns
t _r	Turn-On Rise Time			3.4		ns
t _{D(off)}	Turn-Off DelayTime			16		ns
t _f	Turn-Off Fall Time			2		ns
t _{rr}	Body Diode Reverse Recovery Time	I _F =12A, dI/dt=100A/μs		27	35	ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =12A, dI/dt=100A/μs		30		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

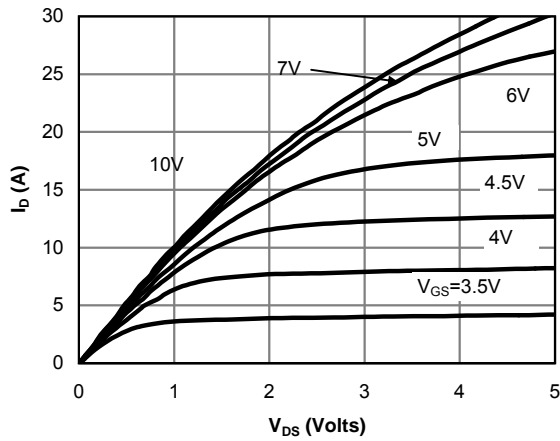


Fig 1: On-Region Characteristics (Note E)

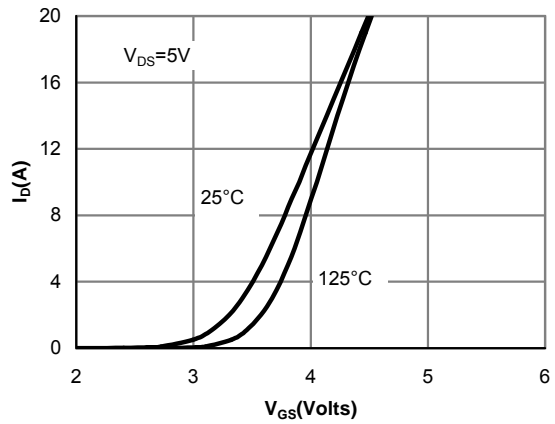


Figure 2: Transfer Characteristics (Note E)

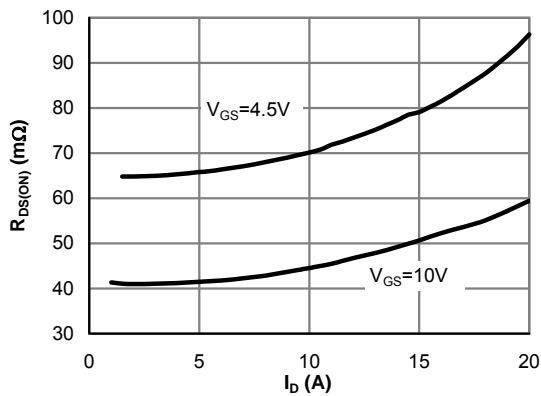


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

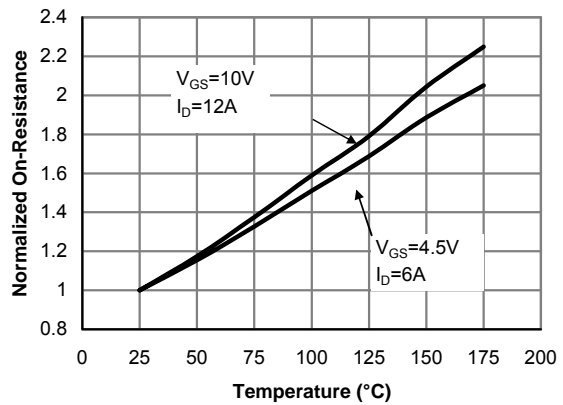


Figure 4: On-Resistance vs. Junction Temperature (Note E)

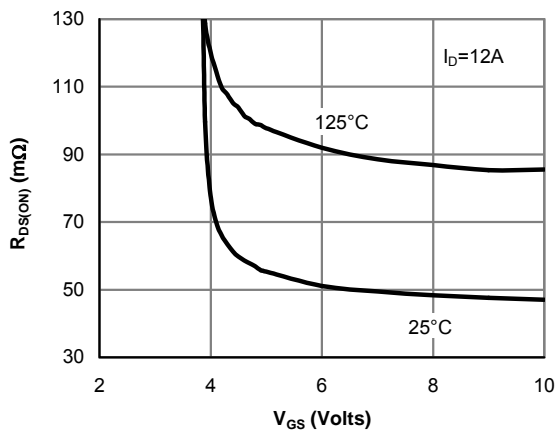


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

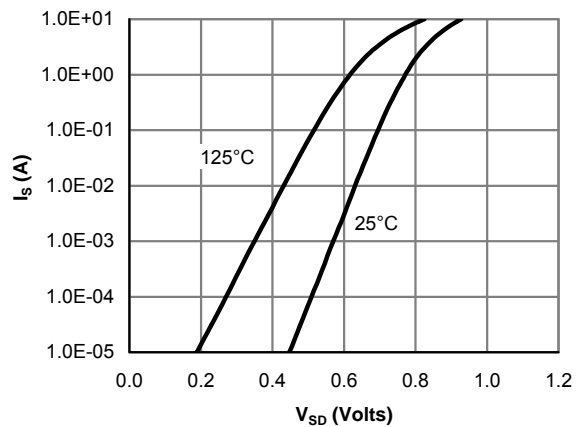


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

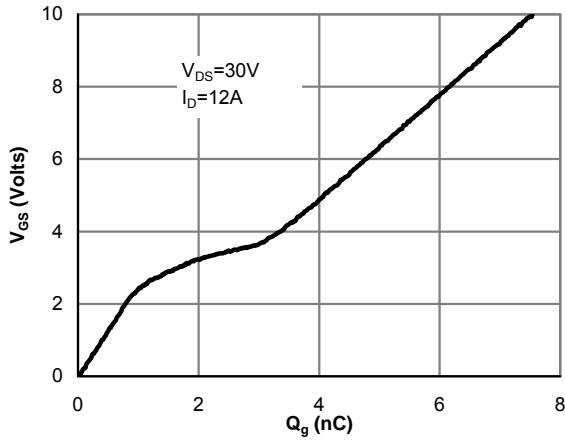


Figure 7: Gate-Charge Characteristics

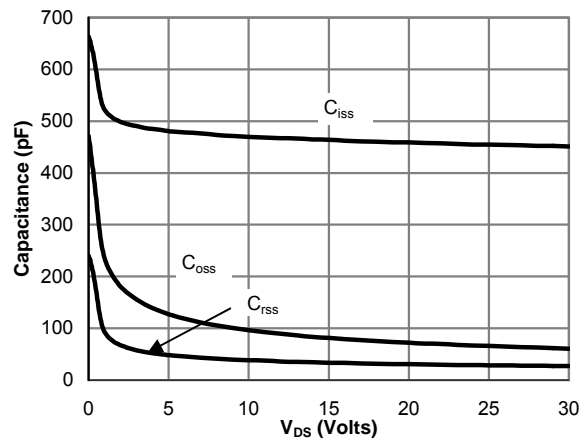


Figure 8: Capacitance Characteristics

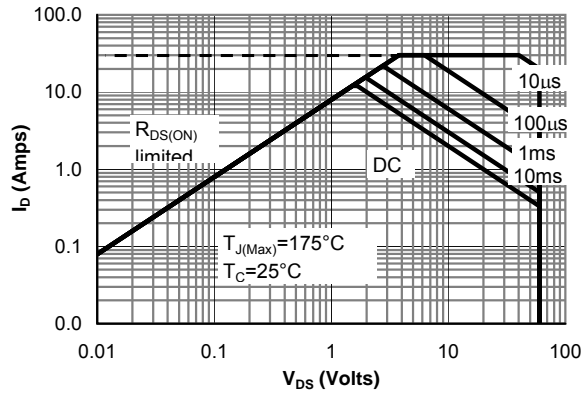


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

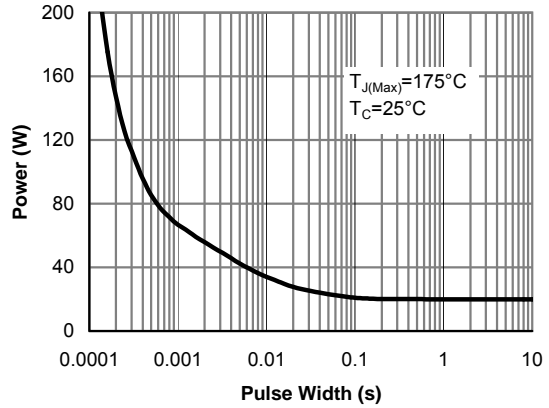


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

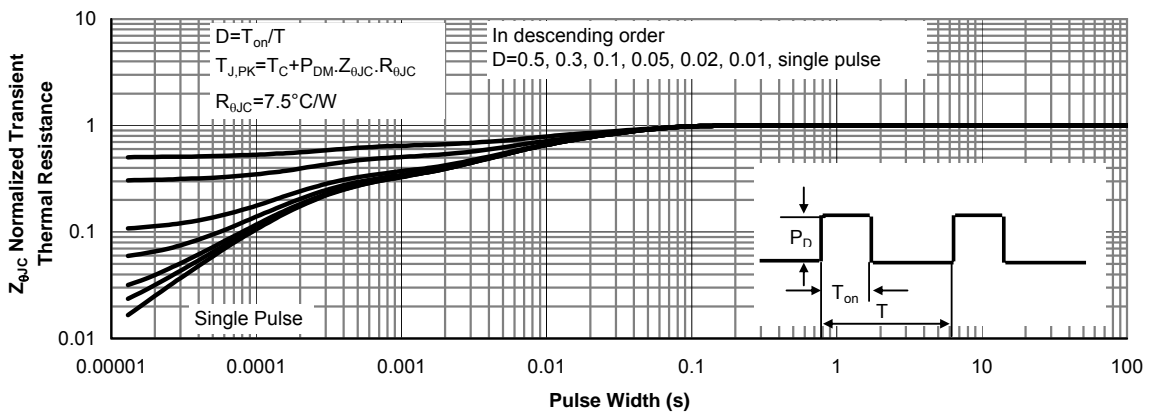


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

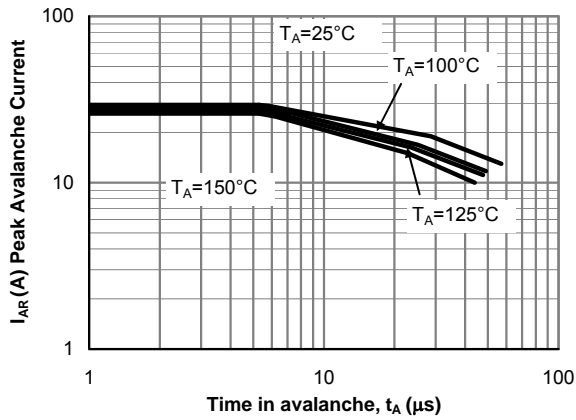


Figure 12: Single Pulse Avalanche capability (Note C)

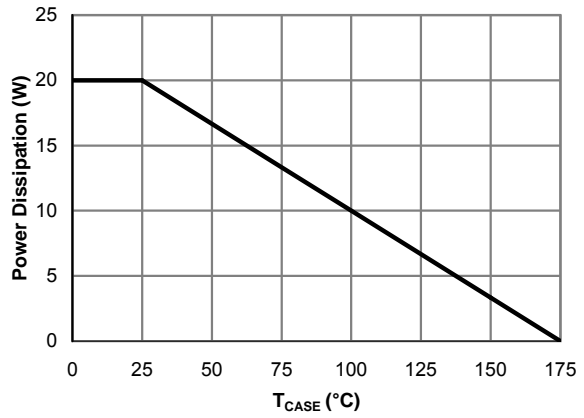


Figure 13: Power De-rating (Note F)

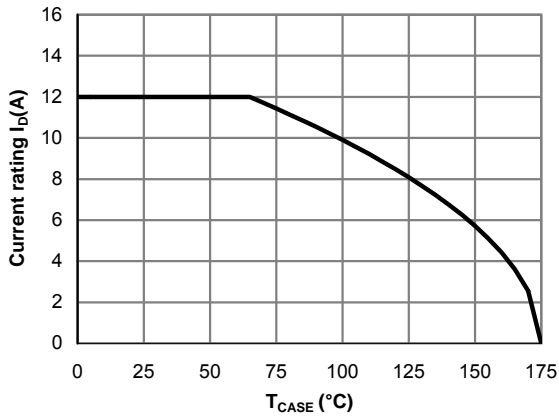


Figure 14: Current De-rating (Note F)

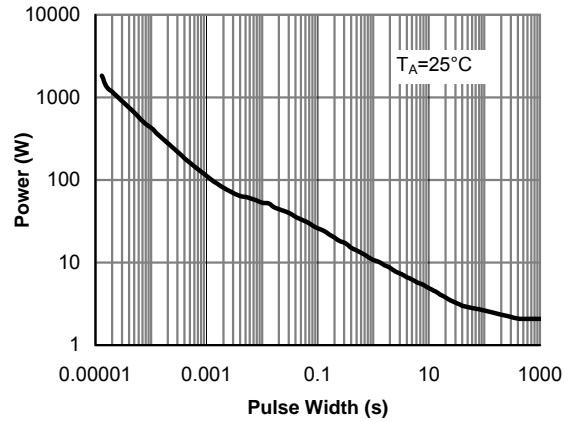


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

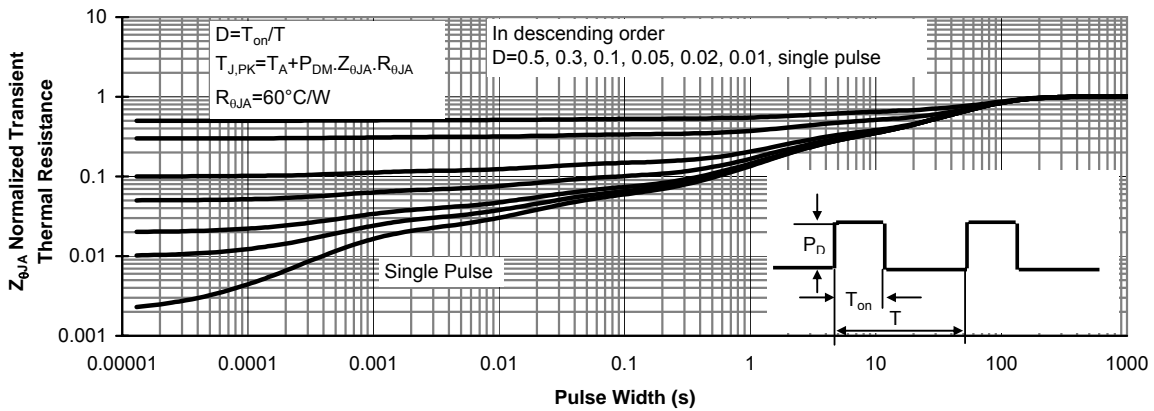
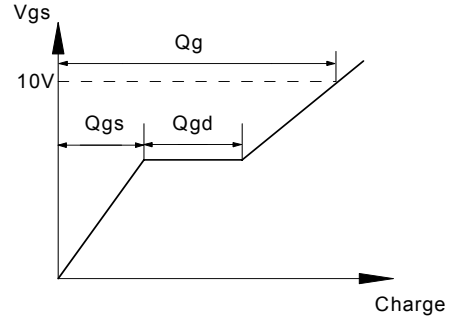
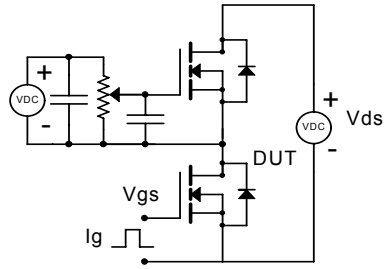
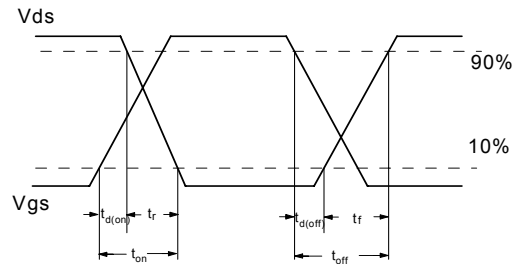
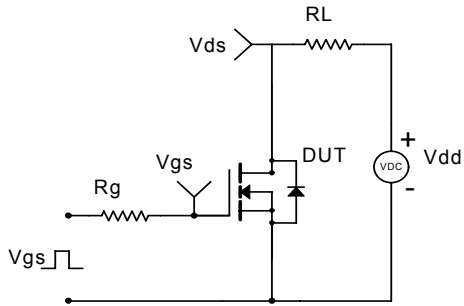


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)

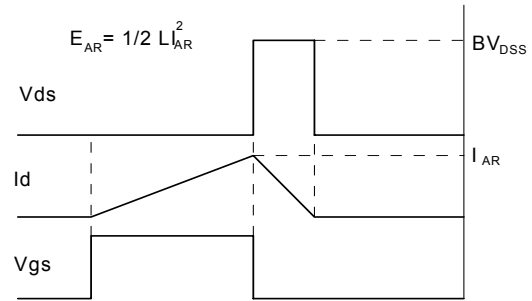
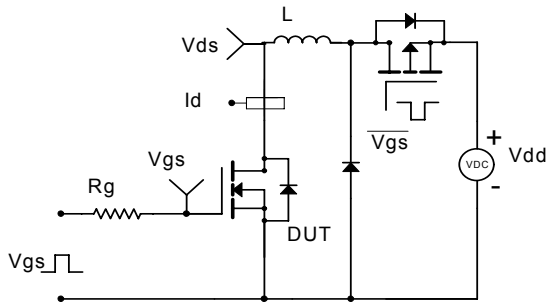
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

